

Electronic Acknowledgement Receipt

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Application Number:	10710826
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Title of Invention:	METHOD OF FORMING STRAINED SILICON MATERIALS WITH IMPROVED THERMAL CONDUCTIVITY
First Named Inventor:	Stephen W. Bedell
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment - After Non-Final Rejection	FIS920040069US1Amend.pdf	307164	no	8

Warnings:	
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Total Files Size (in bytes):	307164
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